Figures 4-5 show the assembly 200 after a second die 30 with electrical contact areas 38 on the die's top surface 36 is pressed against the second adhesive layer 22_b located on the top surface 26 of the first die 20. A cavity 25 is formed between the dies 20 and 30 and is characterized by a distance D between the perimeter 34 of the second adhesive layer 22_b and the perimeter 39 of the second die 30. The distance D may be a regular or irregular distance around the periphery of the adhesive layer 22_b. It is to be understood that formation of cavity 25 is not essential, what is important is that adhesive layer 22_b does not extend beyond the perimeter 39 of the second die 30 such that no adhesive fillet 24_b is formed.

Cancel claims 22, 24-27 and 29-31.